

S2A THRU S2M

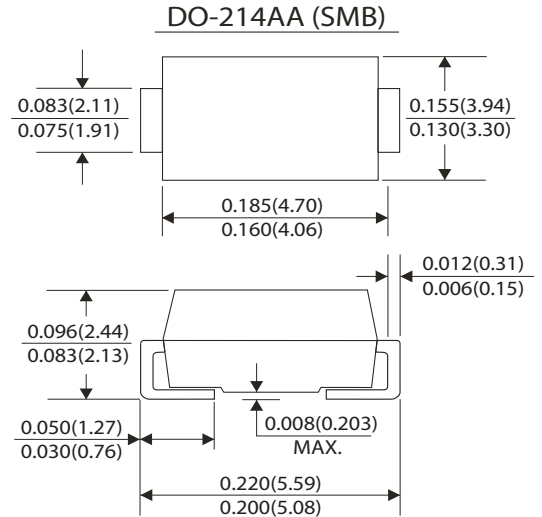
CURRENT 2.0 Amperes
VOLTAGE 50 to 1000 Volts

Features

- For surface mounted applications
- Glass passivated junction
- Low profile package
- Built-in strain relief, ideal for automated placement
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- High temperature soldering guaranteed: 350 °C/10 second, at terminals

Mechanical Data

- Case : JEDEC SMB(DO-214AA) molded plastic body
- Terminals : Plated axial lead solderable per MIL-STD-750, method 2026
- Polarity : Color band denotes cathode end
- Mounting Position : Any
- Weight : 0.003 ounce, 0.093 gram



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

(Ratings at 25 °C ambient temperature unless otherwise specified, Single phase, half wave 60Hz, resistive or inductive load. For capacitive load, derate by 20%)

| | Symbols | S2A | S2B | S2D | S2G | S2J | S2K | S2M | Units |
|--|------------------------------------|-------------|-----|-----|-----|-----|-----|------|-------|
| Maximum recurrent peak reverse voltage | V _{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | Volts |
| Maximum RMS voltage | V _{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | Volts |
| Maximum DC blocking voltage | V _{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | Volts |
| Maximum average forward rectified current at T _L =100 °C | I <sub(av)< sub=""></sub(av)<> | 2.0 | | | | | | | Amps |
| Peak forward surge current 8.3ms half sine wave superimposed on rated load (JEDEC method) T _L =100 °C | I _{FSM} | 50.0 | | | | | | | Amps |
| Maximum instantaneous forward voltage at 2.0A | V _F | 1.15 | | | | | | | Volts |
| Maximum reverse current at rated voltage | T _A =25 °C | 1.0 | | | | | | | μA |
| | T _A =125 °C | 125 | | | | | | | |
| Typical thermal resistance (Note 2) | R _{θJL} | 16.0 | | | | | | | °C/W |
| | R _{θJA} | 53.0 | | | | | | | |
| Typical reverse capacitance (Note 3) | t _{rr} | 2.0 | | | | | | | μS |
| Typical junction capacitance (Note 1) | C _J | 30.0 | | | | | | | pF |
| Operating and Storage temperature Range | T _J T _{STG} | -55 to +150 | | | | | | | °C |

Notes:

- (1) Measured at 1MHz and applied reverse voltage of 4.0V dc.
- (2) Thermal resistance from junction to ambient and from junction to lead mounted on 0.2 × 0.2" (0.5 × 0.5mm) copper pad areas.
- (3) Reverse recovery test conditions: I_F=0.5A, I_R=1.0A, I_{rr}=0.25A



RATINGS AND CHARACTERISTIC CURVES S2A THRU S2M

FIG.1-FORWARD CURRENT DERATING CURVE

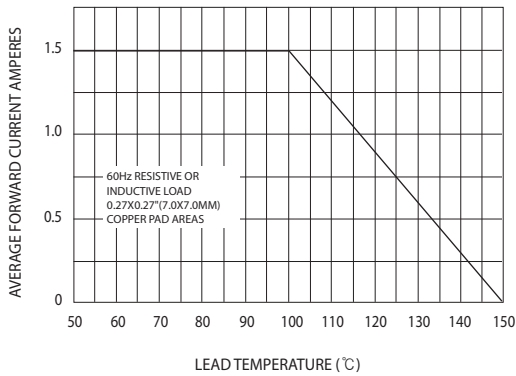


FIG.2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

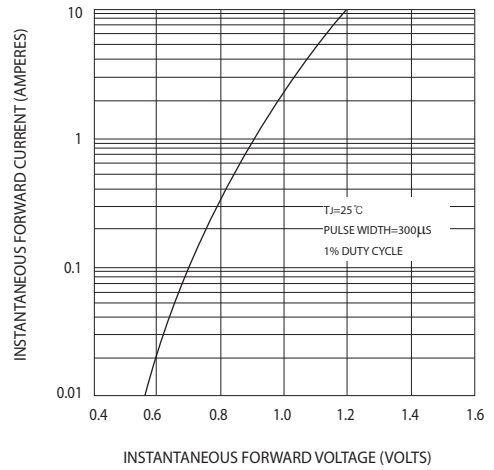


FIG.3-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

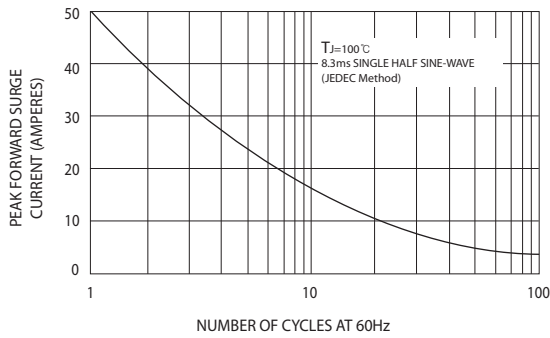


FIG.4-TYPICAL REVERSE CHARACTERISTICS

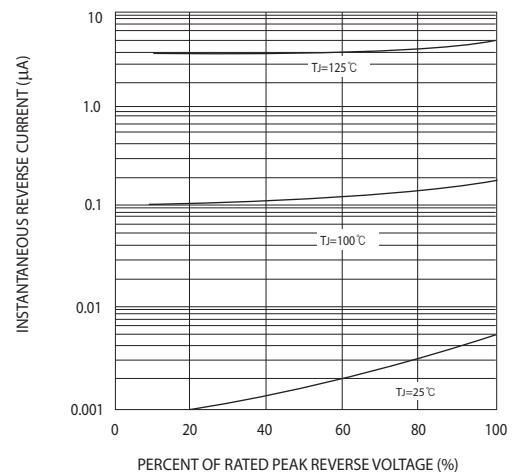


FIG.5-TYPICAL JUNCTION CAPACITANCE

